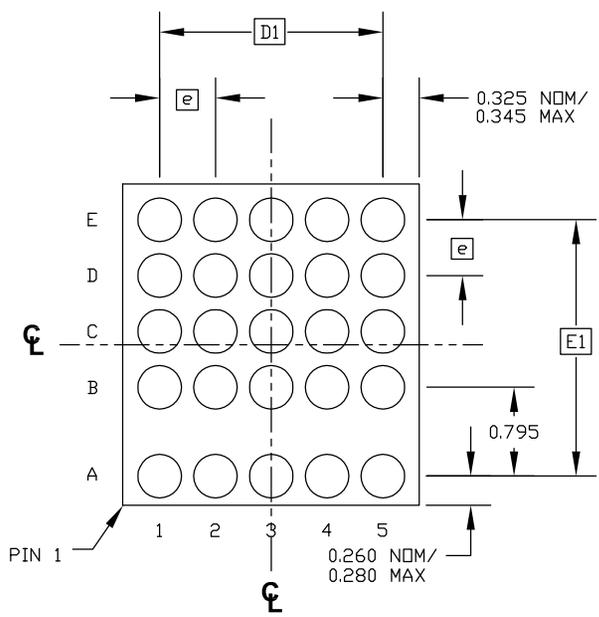


DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.880	0.930	0.980	0.035	0.037	0.039
A1	0.260	0.280	0.300	0.010	0.011	0.012
A2	0.620	0.650	0.680	0.024	0.026	0.027
b	0.340	0.370	0.400	0.013	0.015	0.016
D	2.610	2.650	2.690	0.103	0.104	0.106
D1	2.000 BSC			0.079 BSC		
E	2.830	2.870	2.910	0.111	0.113	0.115
E1	2.295 BSC			0.090 BSC		
e	0.500 BSC			0.020 BSC		
MD	5 BALLS			5 BALLS		
ME	5 BALLS			5 BALLS		
N	25 BALLS			25 BALLS		

BOTTOM VIEW



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MD IS THE BALL MATRIX SIZE IN THE "D" DIRECTION, ME IS THE BALL MATRIX SIZE IN THE "E" DIRECTION, AND N IS THE TOTAL NUMBER OF BALLS FOR THE MATRIX SIZE MD X ME AND DOES NOT INCLUDE BALLS FROM ANY DEPOPULATED LOCATIONS.
3. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M.-2009.
4. PRIMARY DATUM C (SEATING PLANE) IS DEFINED BY THE CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
6. MARKING SHOWN IS FOR PKG. ORIENTATION PURPOSE ONLY.
7. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
8. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODES ONLY.



TITLE:
PACKAGE OUTLINE, 25 BALLS
WLCSP, 0.50mm PITCH, C252B2+1

APPROVAL	DOCUMENT CONTROL NO. 21-0922	REV. A	1/1
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-DRAWING NOT TO SCALE-